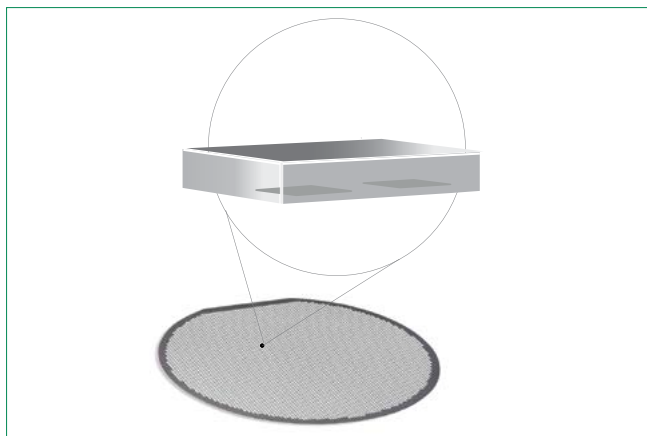


FC09B1606NL-0/FC09B1606NS-0

Flip Chip Zener Die, Bi-directional for ESD Protection



Description

The new FC09B1606Nx-0 is to be designed next to the LED together to provide improved bi-directional ESD protection, and it can safely absorb repetitive ESD strikes above the maximum contact level specified in IEC 61000-4-2 international standard level 4.

Features & Benefits

- Bi-directional
- Enhanced ESD performance
- ESD, IEC 61000-4-2 standard level 4: 8kV contact & 15kV air
- Saves bonding wire in assemble process
- AEC-Q qualified with package SOT-23; qualification report to be provided upon request.
- Optional backside metalization for optical appearance (Al/ SI)

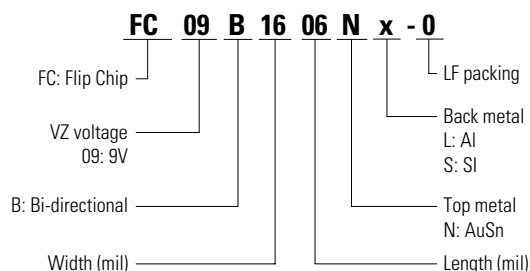
Absolute Maximum Ratings

| Symbol | Parameter | Value | Units |
|--------|-----------------------|-------|-------|
| T_j | Operating Temperature | 150 | °C |

Applications

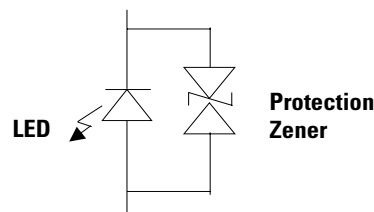
- Handset Flash LED ESD protection
- Auto LED headlight ESD
- Backlight LED in Display TV and Monitor
- Outdoor LED
- Ultraviolet UV light / Sterilamp
- Module embedded ESD die for I/Os

Part Numbering



Functional Diagram

Equivalent Circuit



Electrical Characteristics ($T_{OP}=25\text{ }^{\circ}\text{C}$)

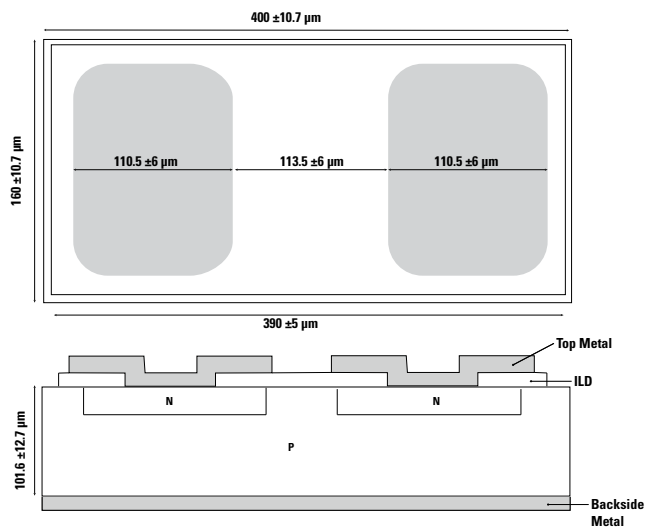
| Parameter | Symbol | Test Conditions | Min | Typ | Max | Units |
|-----------------|-------------------|---------------------------------|-----|-----|------|-------|
| Zener Voltage | $V_z 1$ (Forward) | $I_{zf1}=5\text{ mA}$ | 7.0 | - | 10.5 | V |
| | $V_z 2$ (Forward) | $I_{zf2}=10\text{ }\mu\text{A}$ | 7.0 | - | 10.5 | V |
| | $V_z 1$ (Reverse) | $I_{zf1}=5\text{ mA}$ | 7.0 | - | 10.5 | V |
| | $V_z 2$ (Reverse) | $I_{zf2}=10\text{ }\mu\text{A}$ | 7.0 | - | 10.5 | V |
| Leakage Current | I_{df} | $V=5\text{ V}$ | - | 10 | 500 | nA |
| | I_{dr} | | - | 10 | 500 | nA |

Note: Parameter is guaranteed by package characterization

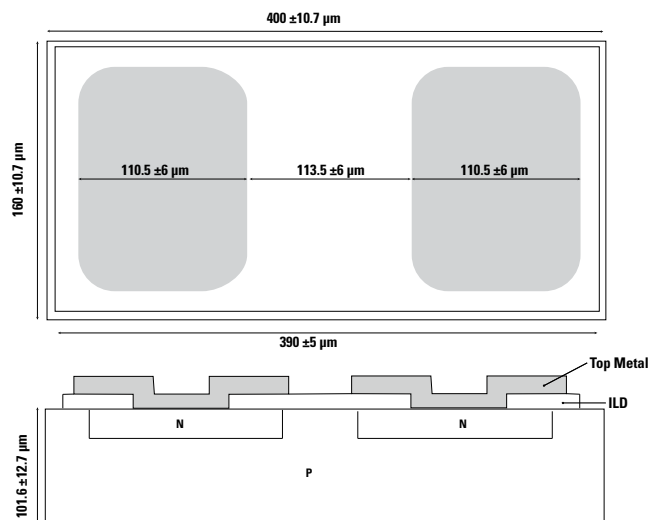
FC09B1606NL-0/FC09B1606NS-0

Flip Chip Zener Die, Bi-directional for ESD Protection

Physical Dimensions



| FC09B1606NL-0 | Characteristics | |
|--------------------|-------------------|-----------------------|
| Die size | 400*160 ±10.7 μm | 15.75*6.3 ± 0.42 mil |
| Pad size | 110.5 ± 6.0 μm | 4.35 ± 0.20 mil |
| Die thickness | 101.6 ± 12.7 μm | 4.00 ± 0.50 mil |
| Top metalization | SnAu 20 / 80 3 μm | SnAu 20 / 80 0.12 mil |
| Back metallization | Al | |



| FC09B1606NS-0 | Characteristics | |
|------------------|-------------------|-----------------------|
| Die size | 400*160 ±10.7 μm | 15.75*6.3 ± 0.42 mil |
| Pad size | 110.5 ± 6.0 μm | 4.35 ± 0.20 mil |
| Die thickness | 101.6 ± 12.7 μm | 4.00 ± 0.50 mil |
| Top metalization | SnAu 20 / 80 3 μm | SnAu 20 / 80 0.12 mil |
| Back material | SI | |

Packing Specification

For detail packing size or specification, please contact Littelfuse.

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